



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-11-10
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Laurent TOSI	<b>Representative Title</b>	MMS MD CHAMPION
<b>Representative Phone *</b>	33 442 685 795	<b>Representative Email *</b>	<a href="mailto:laurent.tosi@st.com">laurent.tosi@st.com</a>
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST25TA512-AC6F5	CBG9*TAIA0UA	A	994I	2017-11-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	0.30	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NAC	NAC		

Package Designator	Size	Nbr of instances	Shape	
CHP	0.680x0.771x0.12	4	No lead	
Comment	Bumped Bare Die			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CBG9*TAIA0UA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die	M-011 Other inorganic materials	0.2910	mg	supplier	die	Silicon (Si)	7440-21-3		0.2650	mg	910653	870565
				supplier	metallization	Aluminium (Al)	7429-90-5		0.0020	mg	6873	6570
				supplier	metallization	Copper (Cu)	7440-50-8		0.0020	mg	6873	6570
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.0020	mg	6873	6570
				supplier	passivation	Indium Tin oxide ( In2O3:SnO2 )	50926-11-9		0.0200	mg	68729	65703
Bump	M-011 Other inorganic materials	0.0081	mg	supplier	Bump metallization	Gold (Au)	7440-57-5		0.0081	mg	1000000	26772
Polyimide	M-011 Other inorganic materials	0.0052	mg	supplier	Polyimide	Polyamic acid ester	Proprietary		0.0040	mg	770000	13196
				supplier	Polyimide	Tetraethylene glycol dimethacrylate	109-17-1		0.0005	mg	90000	1542
				supplier	Polyimide	Other components	Proprietary		0.0007	mg	140000	2399